



# P/N 1110087 144-Pin VQFP-to-PGA Adapter

## FEATURES

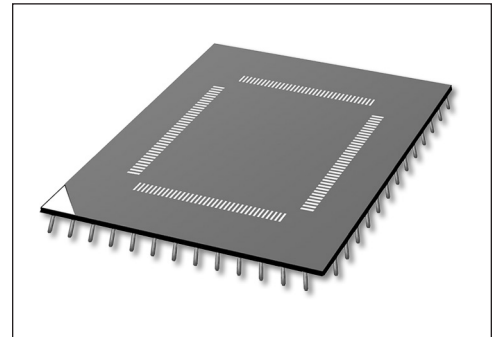
- Convert surface-mount VQFP packages to a 13 x 13 PGA footprint.
- Reduce costs by using less-expensive QFP packages to replace PGA footprints in existing designs.
- Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact.
- Consult factory for Panelized Form or for mounting of consigned chips.

## GENERAL SPECIFICATIONS

- ADAPTER BODY: FR-4 with 1-oz. Cu traces
- PADS: ENIG (Au over Ni) plated to eliminate coplanarity concerns
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: 200 $\mu$  [5.08 $\mu$ ] Sn/Pb 93/7 per ASTM B579-73 over 100 $\mu$  [2.54 $\mu$ ] Ni per SAE-AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

## MOUNTING CONSIDERATIONS

- Suggested PCB Hole Size: 0.028  $\pm$  0.003 [0.71  $\pm$  0.08] dia.
- Will plug into Standard PGA Sockets.



**CUSTOMIZATION:** In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

## ORDERING INFORMATION

P/N 1110087

P/N 1110087-P for Panelized Form

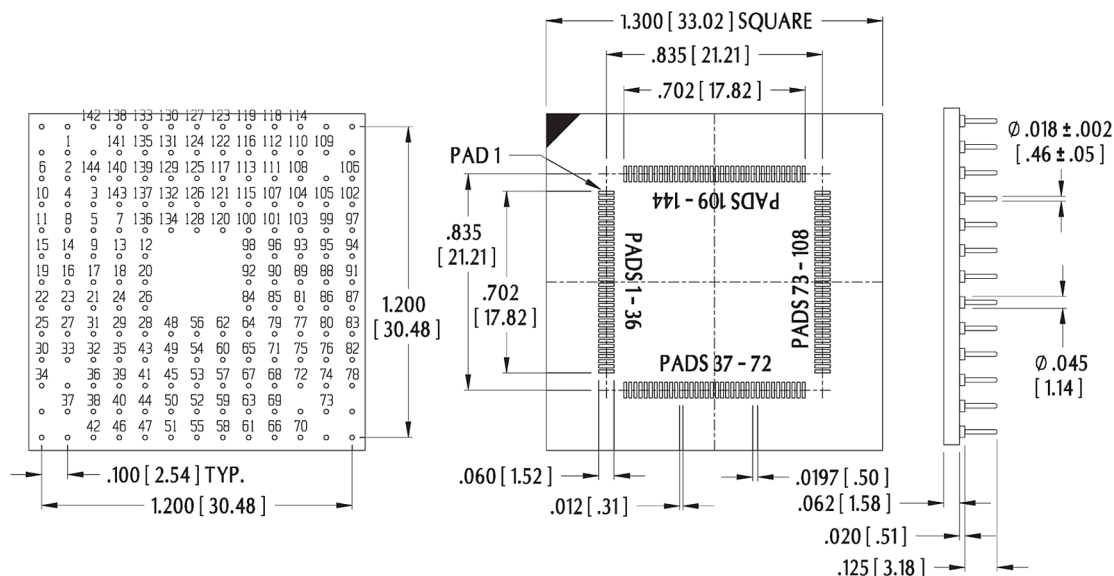
ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES:  $\pm$ 0.005 [0.13] UNLESS OTHERWISE SPECIFIED

ROW-TO-ROW  $\pm$ 0.003 [ $\pm$ 0.08]

PIN-TO-PIN  $\pm$ 0.003 [ $\pm$ 0.08] NON-CUMULATIVE

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



X-RAY VIEW TOP SIDE  
QFP PAD ASSIGNMENT

TOP (QFP) SIDE



**ARIES**  
ELECTRONICS, INC.

Bristol, PA 19007-6810 USA  
TEL (215) 781-9956 • FAX (215) 781-9845  
WWW.ARIESELEC.COM • INFO@ARIESELEC.COM